

PRODUCT SPECIFICATION

7.0" TFT LCD MODULE MODEL: YDP LCD I 700 LVDS Ver:1.0

< <> Preliminary Specification

< >> Finally Specification

	CUSTOMER'	S APPROVAL
CUSTOMER:		
SIG	NATURE:	DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
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Revision History

Date	Originator	Detail	Remarks
2023.10.27	LQ	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	7.0"	
LCD type	IPS TFT	
Display Mode	Transmissive/Normally Black	
Resolution	800 RGB x 480	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	164.9(H) x 100.0(V) x 3.35(T) (Note1)	mm
Active Area	153.84(H) x 85.632(V)	mm
Pixel Pitch	192.3 (H) x 178.4(V)	um
Pixel Arrangement	RGB vertical Stripe	
Polarizer Surface Treatment	Glare	
Display Colors	16.7 M	
Interface	LVDS	
Driver IC	ST7277	-
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	107	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

ltem	Symbol	Min.	Max.	Unit
Dower oupply yelte go	VDD	-0.3	4.0	V
Power supply voltage	VDDI	-0.3	4.0	V
Storage temperature	T _{STG}	-30	+80	°C
Operating temperature	Тор	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

ltem	Symbol	Min.	Тур.	Max.	Unit
Supply Valtage	VDD	3.1	3.3	3.6	V
Supply Voltage	VDDI	3.1	3.3	3.6	V
Differential Input High Threshold Voltage	RxVTH	-	-	0.1	V
Differential Input Low Threshold Voltage	RxVTL	-0.1	-	-	V
Input Voltage Range (Singled-End)	RxVIN	0	-	VDD-1.0	V
Differential Input Common Mode Voltage	RxVCM	VID /2	-	2.4- VID /2	V
Differential Input Voltage	VID	0.2	-	0.6	V
Current Consumption All white	I _{DD+} I _{DDI}	-	80	-	mA

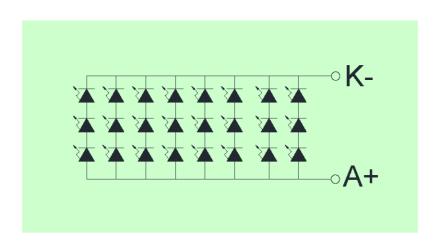
5. Backlight Characteristic

5.1. Backlight Characteristic

ltem	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	Ta=25 °C, I _F =20mA	8.4	9.6	10.2	٧
Forward Current	lF	Ta=25 °C, V _F =3.2V/LED	-	160	-	mΑ
Power dissipation	Po		1	1536	1	mW
Uniformity	Avg		-	80	-	%
LED working life(25°C)	-		-	30,000	-	Hrs
Drive method		Constant	current			
LED Configuration	24	1 White LEDs(3 LEDs in one	string and	l 8 groups	in paralle	·l)

Note 1: LED life time defined as follows: The final brightness is at 50% of original brightness. The environmental conducted under ambient air flow, at Ta=25 \pm 2 °C,60%RH \pm 5%, I_F=20mA.

5.2. Backlighting circuit



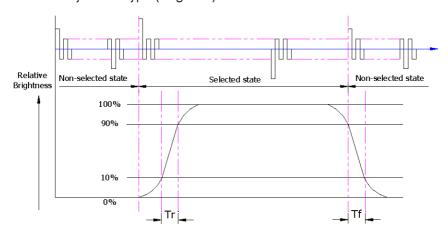
6. Optical Characteristics

Ta=25°C, VDD=3.3V

	Ite	m	Sumbol	Condition	S	pecificati	on	Unit
	itei	TI	Symbol	Condition	Min.	Тур.	Max.	Offic
	Luminar	nce on						
	TFT(I_f =20)mA/LED)	Lv		320	400	-	cd/m²
ا ش	Contrast rati	o(See 6.3)	CR		800	1000	-	
On (Transmissive Mode)	Respons (See		TR+TF		-	25	-	ms
] š		Red	Xr		0.548	0.598	0.648	
nis		Rea	Yr		0.299	0.349	0.399	
nsr	Chromoticity	Green	Xg		0.272	0.322	0.372	
Tra	Chromaticity Transmissive	Gieen	Yg		0.543	0.593	0.643	
) 	(See 6.5)	Blue	Хв		0.106	0.156	0.206	
	(000 0.0)	blue	Yв		0.092	0.142	0.192	
lig		White	Xw		0.261	0.311	0.361	
Backlight		vville	Yw		0.289	0.339	0.389	
Ä	Viewing	Horizontal	Өх+		-	85	ı	
	Viewing Angle	rionzoniai	Өх-	Center CR≥10	-	85	-	Deg.
	(See 6.4)	Vertical	φΥ+	Center Cive 10	-	85	-	Deg.
	(000 0.4)	vertical	φΥ-		-	85	-	
	NTSC Rati	o(Gamut)			-	50	-	%

6.1. Definition of Response Time

6.1.1. Normally Black Type (Negative)

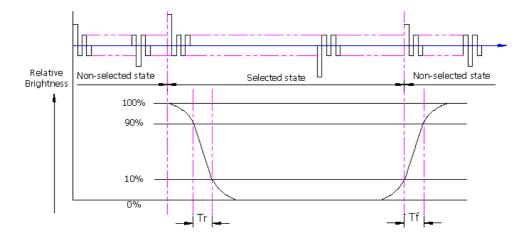


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.1.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

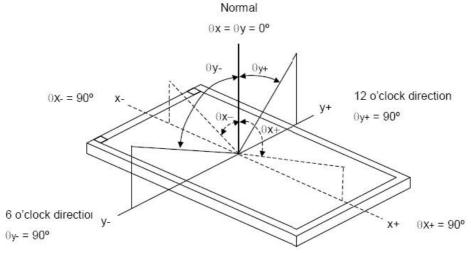
6.2. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Took worth own	A: All Pixels white
Test pattern	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.3. Definition of Viewing Angles

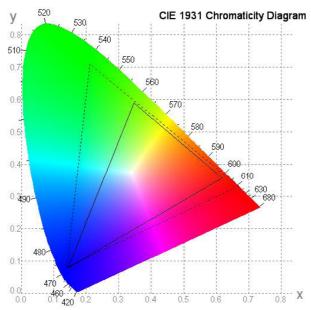


Measuring machine: LCD-5100 or EQUI

6.4. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

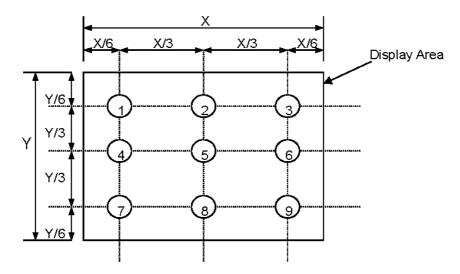


6.5. Definition of Surface Luminance, Uniformity and Transmittance

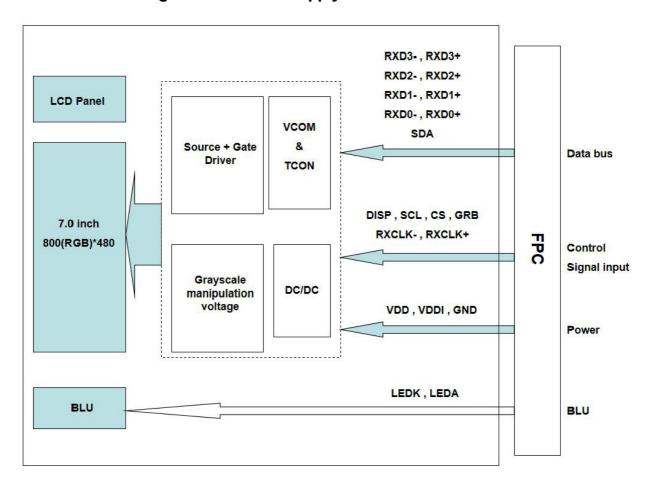
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.5.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.5.2. Uniformity = Minimal (L_{P1}:L_{P9}) / Maximal (L_{P1}:L_{P9}) * 100%
- 6.5.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

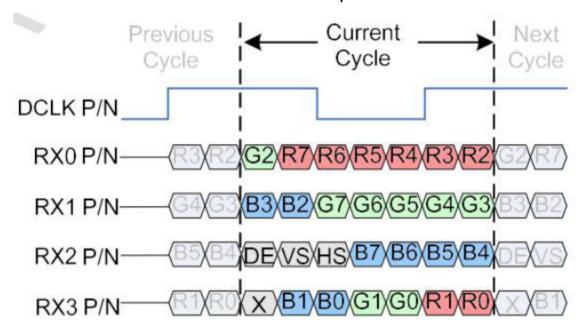


8. Interface Pins Definition

No.	Symbol	Function
1	GND	Ground
2		DISP sets the display mode.
	DISP	L:Standby mode(Default)
		H:Normal display mode
3	SCL	Serial communication clock input.
4	SDA	Serial communication data input and output.
5	CS	Serial communication chip selection.
6	GRB	Global reset pin. When GRB is "L", internal initialization procedure is executed.
7	GND	Ground
8	RXD0+	LVDS differential signal data input0+
9	RXD0-	LVDS differential signal data input0-
10	GND	Ground
11	RXD1+	LVDS differential signal data input1+
12	RXD1-	LVDS differential signal data input1-
13	GND	Ground
14	RXD2+	LVDS differential signal data input2+
15	RXD2-	LVDS differential signal data input2-
16	GND	Ground
17	RXD3+	LVDS differential signal data input3+
18	RXD3-	LVDS differential signal data input3-
19	GND	Ground
20	RXCLK+	+LVDS differential clock input.
21	RXCLK-	-LVDS differential clock input.
22	GND	Ground
23	VDDI	power supply
24	VDD	power supply
25	NC	No Connection
26	NC	No Connection
27	LEDA	LED Anode
28	LEDK	LED Cathode
29	GND	Ground
30	GND	Ground

9. AC Characteristics

9.1. 4 Lane JEIDA Data Format Color Bit Map



9.2. Parallel 24-bit RGB Input Timing Table

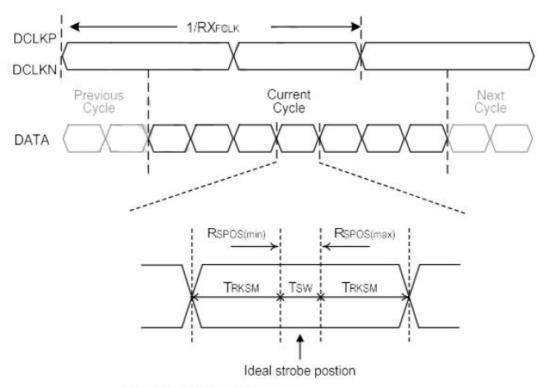
Parallel 24-bit RGB Input Timing (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C).

		Parallel 24	bit RGE	Interfa	ce Timir	ng Table	
Item Symbol Min. Typ. Max. Unit Remark							
DCL	Frequency	Fclk	23	25	27	MHz .	4
HSYNC	Period Time	Th	808	816	848	DCLK	
	Display Period	Thdisp		800		DCLK	
	Back Porch	Thbp	4	8	24	DCLK	
	Front Porch	Thfp	4	8	24	DCLK	
	Pulse Width	Thw	2	4	8	DCLK	
	Period Time	Tv	496	512	528	HSYNC	
	Display Period	Tvdisp		480		HSYNC	
VSYNC	Back Porch	Tvbp	8	16	24	HSYNC	
	Front Porch	Tvfp	8	16	24	HSYNC	
	Pulse Width	Tvw	2	4	8	HSYNC	

Note: 1. The minimum blanking time depends on the GIP timing of the panel specification.

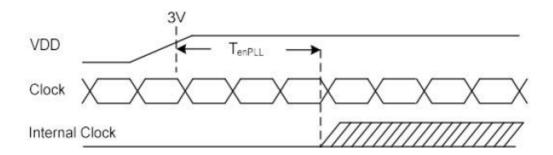
- 2. To ensure the compatibility of different panels, it is recommended to use the typical setting.
- 3. It is necessary to keep Tvbp =16 and Thbp =8 in sync mode. DE mode is unnecessary to keep it.
- 4. The maximum DCLK Frequency is 27MHz. If the case needs faster DCLK, please contact Sitronix.

9.3. LVDS Input Timing



RRKSM: Receiver strobe margin RSPOS: Receiver strobe position

Tsw: Strobe width (internal DATA sampling window)



LVDS Input Timing (PVDD=VDD=VDDI= 3.3V, AGND= 0V, TA=25°C).

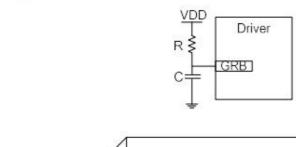
Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
Clock Frequency	RXFCLK	23	25	27	MHz	
Input Data Skew Margin	T _{RSKM}	400	-	- 5	ps	
Clock High Time	TLVCH	4/	7 x RXFC	:LK)	ns	
Clock Low Time	T _{LVCL}	3/(7 x RXFCLK)		ns		
PLL Wake-up Time	TenPLL	2	2	150	us	
LVDS Spre	ad Spectrum Cloc	king (SS	C) Tolera	ance of L	VDS Receiv	er
Modulation Frequency	SSC _{MF}	-	-	100	KHz	
Modulation Rate	SSCMR	-	2	+/-3	%	

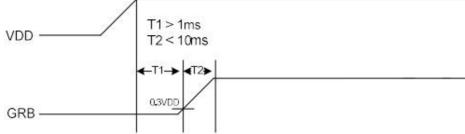
Note. The maximum RXFCLK Frequency is 27MHz. If the case needs faster RXFCLK, please contact Sitronix.

9.4. Reset timing

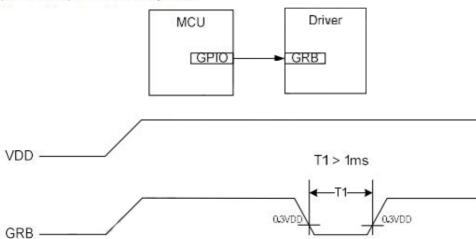
Setting GRB pin to "L" (hardware reset) can initialize internal function. Initialized by GRB pin is essential before operating. There are two suggestions for hardware reset connection.

(1) The GRB pin with external RC circuit.





(2) The GRB pin controlled by MCU.



10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
 - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
 - 10.3.2.1. Non-conforming product over PPM level will be replaced.
 - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4.Agreement Items

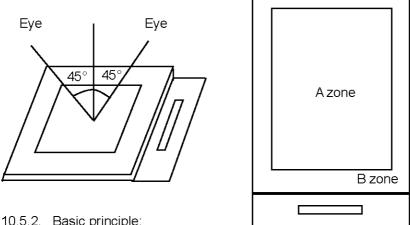
Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
 - 10.5.1.1. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
 - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



10.5.2. Basic principle:

10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

10.5.2.2. New item must be added on time when it is necessary.

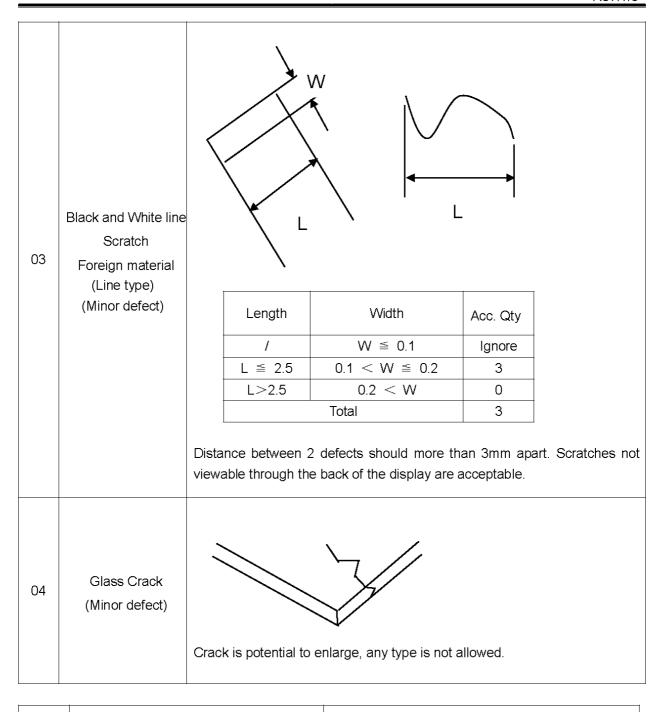
10.6.Inspection Specification for the TFT module

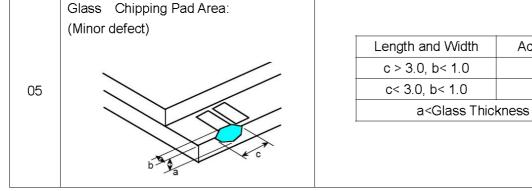
No.	Item	Criteria (Unit: mm)			
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b) /2 Distance between 2 defects show	Size φ≤0 0.20<φ 0.50	o≤0.50 o<φ	Acc. Qty Ignore N≤3 0
	Electrical Defect (Minor defect)	II Bright dot 	olay Area N ≤2	Total N≤2	Natad
		Dark dot	N≤4	N≤4	Note1
02		Total dot	N≤4	N≤4	
02		Mura Not visible through 5% ND filters.			Note 2
		Remark: 1. Bright dot caused by scratch a	and foreign c	object accords to	item 1.

Acc. Qty

1

3





	Glass Chipping Rear of Pad Area: (Minor defect)					
	(Willion derect)	Г	Length and Width	Acc. Qty		
			c > 3.0, b< 1.0	1		
06			c< 3.0, b< 1.0	2		
			c< 3.0, b< 0.5	4		
			a <glass td="" thick<=""><td>kness</td></glass>	kness		
	b a					
	Glass Chipping Except Pad Area: (Minor defect)					
			Length and Width	Acc. Qty		
			c > 3.0, b< 1.0	1		
07			c< 3.0, b< 1.0	2		
			c< 3.0, b< 0.5	4		
	0 3		a <glass td="" thicl<=""><td>kness</td></glass>	kness		
	a	a solds illioniess				
	Glass Corner Chipping: (Minor defect)					
		Г	Length and Width	Acc. Qty		
			c < 3.0, b< 3.0	Ignore		
08			a <glass td="" thickness<=""></glass>			
		-				
	ba					
	Glass Burr:					
	(Minor defect)		Length	Acc. Qty		
			F < 1.0	Ignore		
		-				
		Glass	burr don't affect ass	semble and module		
		dimens	sion.			
09						
	F					
	E					
	→ -					

	FPC Defect:						
	(Minor defect)						
10	a		10.1 Dent, pinhole	width a <w 3.<="" td=""><td></td></w>			
	a To		(w: circuitry width.)	(w: circuitry width.)			
10	w →	w —		10.2 Open circuit is unacceptable.			
			10.3 No oxidation, contamination and distortion.				
	a—II		Total transmissing				
			Diameter	Acc. Qty			
11	Bubble on Polarizer		φ≤0.30	Ignore			
	(Minor defect)		0.30 <φ≤0.50 N≤2				
			0.50 < φ	N=0			
			Diameter	Acc. Qty			
	Dent on Polarizer		φ≤0.25	Ignore			
12			0.25 <φ≤0.50	N≤4	-		
	(Minor defect)		0.50 < φ	None			
			υ.ου τ φ	TAOLIC			
13	Bezel	13.1 No rust, distortion on the Bezel.					
	20201	13.2 No visible fingerprints, stains or other contamination.					
		d 4 d Nie dietertiere en entermination en DOD termination					
		14.1 No distortion or contamination on PCB terminals.					
14	PCB	14.2 All components on PCB must same as documented on the					
14		BOM/component layout.					
		14.3 Follow IPC-A-600F.					
15	Soldering	Follow IPC-A-610C standard					
		The below defects must be rejected.					
		16.1 Missing ver	lissing vertical / horizontal segment,				
		16.2 Abnormal E	6.2 Abnormal Display.				
		16.3 No function or no display.					
16		16.4 Current exceeds product specifications.					
	(Major defect)	16.5 LCD viewir	6.5 LCD viewing angle defect.				
		16.6 No Backligi					
		16.7 Dark Backlight.					
		16.8 Touch Pane	-				

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

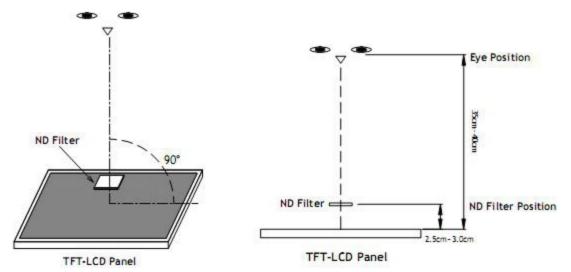
10.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min ~ 70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Floatrical Otatic Discharge	Air:±4KV 150pF/330 Ω	2	GB/T17626.2 -2018
	Electrical Static Discharge	Contact: ±2KV 150pF/330 Ω	∠	
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1. Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3. Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

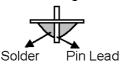
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

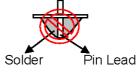
Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



Recommended



Not Recommended

12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
- 12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

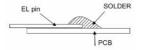
Typical Soldering Time: ≤2s

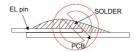
Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting





Recommended

Not Recommended

12.4.2.7. The type of the solder iron:



Recommended

Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7.Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD